Supplier Name:	**Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info:	ti.com/support
Form/Declaration Type:	**Distribute - RoHS and IEC 62474 DB**
Created on:	**06/08/2022**

Details for "TLE2141MD"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
TLE2141MD	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D | 8	3.91x4.9x1.58	82.2

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Precious Metals	Gold	7440-57-5	0.06714	99.998511	999985	0.081634	816
Precious Metals	Silver	7440-22-4	0.000001	0.001489	15	0.000001	0
Sub-Total			**0.067141**	**100**	**1000000**	**0.081635**	**816**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.281806	70	700000	0.342641	3426
Thermoplastics	Epoxy	85954-11-6	0.120774	30	300000	0.146846	1468
Sub-Total			**0.40258**	**100**	**1000000**	**0.489488**	**4895**
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	29.491199	294912
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.726608	7266
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.009083	91
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.009083	91
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.009083	91
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.030275	303
Sub-Total			**24.9**	**100**	**1000000**	**30.27533**	**302753**
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.431968	4320
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003542	35
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.01862	186
Sub-Total			**0.3735**	**100**	**1000000**	**0.45413**	**4541**
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	41.674518	76	760000	50.671076	506711
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	1.919221	3.5	35000	2.333536	23335
Other Plastics and Rubber	Carbon Black	1333-86-4	0.164505	0.300001	3000	0.200018	2000
Thermoplastics	Epoxy	85954-11-6	11.076648	20.2	202000	13.467838	134678
Sub-Total			**54.834892**	**100**	**1000000**	**66.672468**	**666725**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.667068	100	1000000	2.026949	20269
Sub-Total			**1.667068**	**100**	**1000000**	**2.026949**	**20269**
Total			82.245181			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
Created on: 06/08/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.